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(12) **United States Design Patent** (10) **Patent No.: US D874,411 S**
**Kanda et al.** (45) **Date of Patent: ** Feb. 4, 2020**

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(54) **SEMICONDUCTOR MODULE**

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(73) Assignee: **ROHM CO., LTD.**, Kyoto (JP)

(**) Term: **15 Years**

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(22) Filed: **Oct. 9, 2018**

(30) **Foreign Application Priority Data**

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Apr. 13, 2018 (JP) ................................ 2018-008226

(51) **LOC (12) Cl.** ................................ **13-03**
(52) **U.S. Cl.**
USPC ................................ **D13/182**
(58) **Field of Classification Search**
USPC ................................ D13/182
(Continued)

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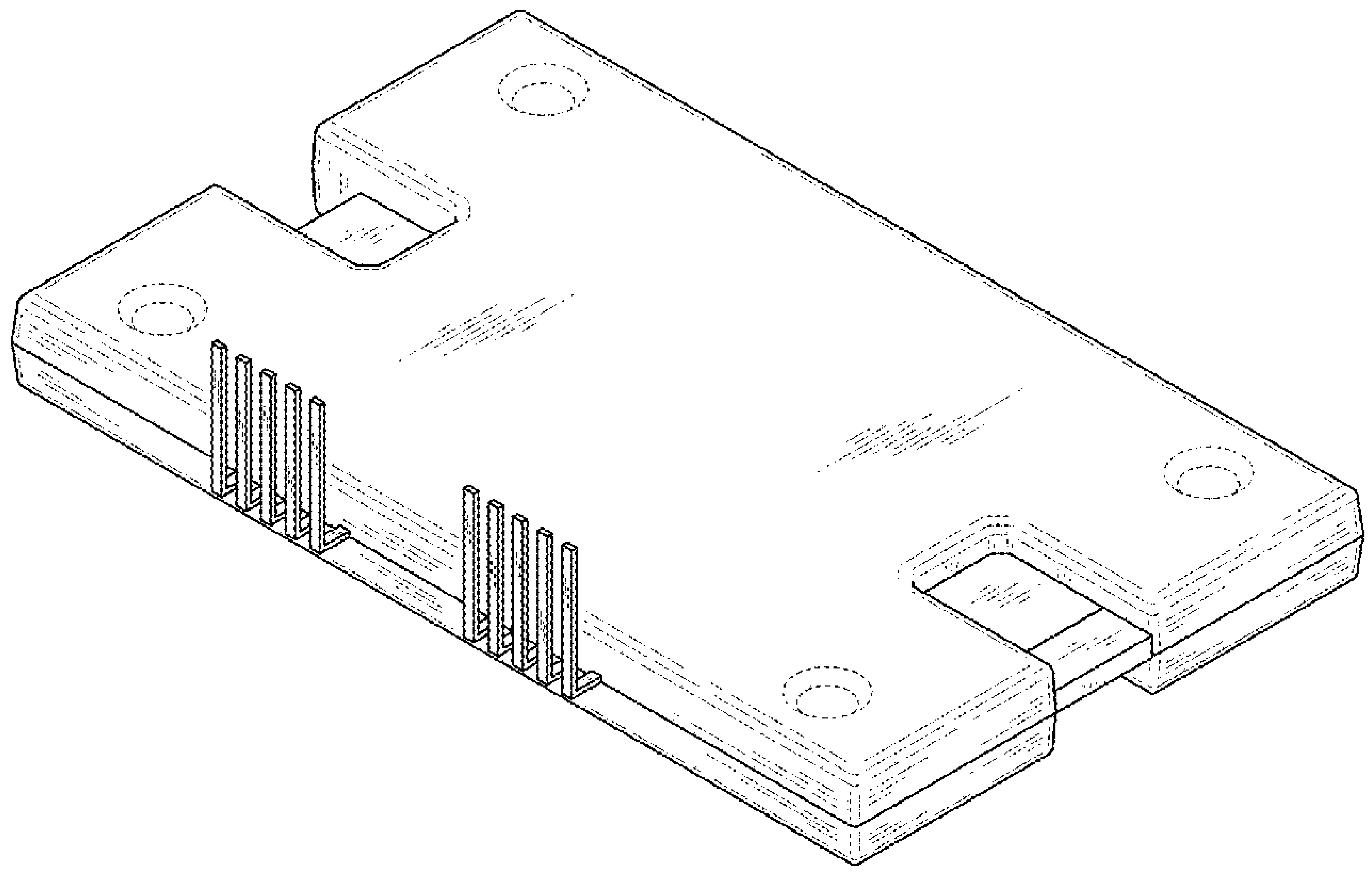
(57) **CLAIM**

The ornamental design for a semiconductor module, as shown and described.

## DESCRIPTION

FIG. **1** is a front, top and right side perspective view of a first embodiment of a semiconductor module showing our new design;
FIG. **2** is a rear, bottom, and left side perspective view thereof;
FIG. **3** is a front view thereof;
FIG. **4** is a rear view thereof;
FIG. **5** is a top plan view thereof;
FIG. **6** is a bottom plan view thereof;
FIG. **7** is a right side view thereof;
FIG. **8** is a left side view thereof;
FIG. **9** is a cross-sectional view taken along line **9-9** in FIG. **5**;
FIG. **10** is a cross-sectional view taken along line **10-10** in FIG. **5**;
FIG. **11** is a front, top and right side perspective view of a second embodiment of a semiconductor module showing our new design;
FIG. **12** is a rear, bottom, and left side perspective view thereof;
FIG. **13** is a front view thereof;
FIG. **14** is a rear view thereof;
FIG. **15** is a top plan view thereof;
FIG. **16** is a bottom plan view thereof;
FIG. **17** is a right side view thereof;
FIG. **18** is a left side view thereof;
FIG. **19** is a cross-sectional view taken along line **19-19** in FIG. **15**; and,
FIG. **20** is a cross-sectional view taken along line **20-20** in FIG. **15**.
The broken lines illustrate portions of the semiconductor module and form no part of the claimed design. The member illustrated with fine, diagonal, parallel lines in FIG. **2** and FIG. **6** is transparent.

**1 Claim, 20 Drawing Sheets**



(58) **Field of Classification Search**

CPC ........... H01L 21/02428; H01L 21/0243; H01L 21/02494; H01L 21/02496; H01L 21/02499; H01L 21/02502; H01L 21/02505; H01L 21/02507; H01L 21/0251; H01L 21/02513; H01L 21/02587; H01L 21/0259; H01L 21/02592; H01L 21/02595; H01L 21/02598; H01L 21/02603; H01L 21/02606; H01L 23/04; H01L 23/041; H01L 23/043; H01L 23/045; H01L 23/047; H01L 23/049; H01L 23/051; H01L 23/053; H01L 23/055; H01L 23/057; H01L 23/06; H01L 23/08; H01L 23/10; H01L 23/452; H01L 23/4922; H01L 29/02; H01L 29/04; H01L 29/045; H01L 29/06; H01L 29/0603; H01L 29/0657; H01L 29/0665; H01L 29/0684

See application file for complete search history.

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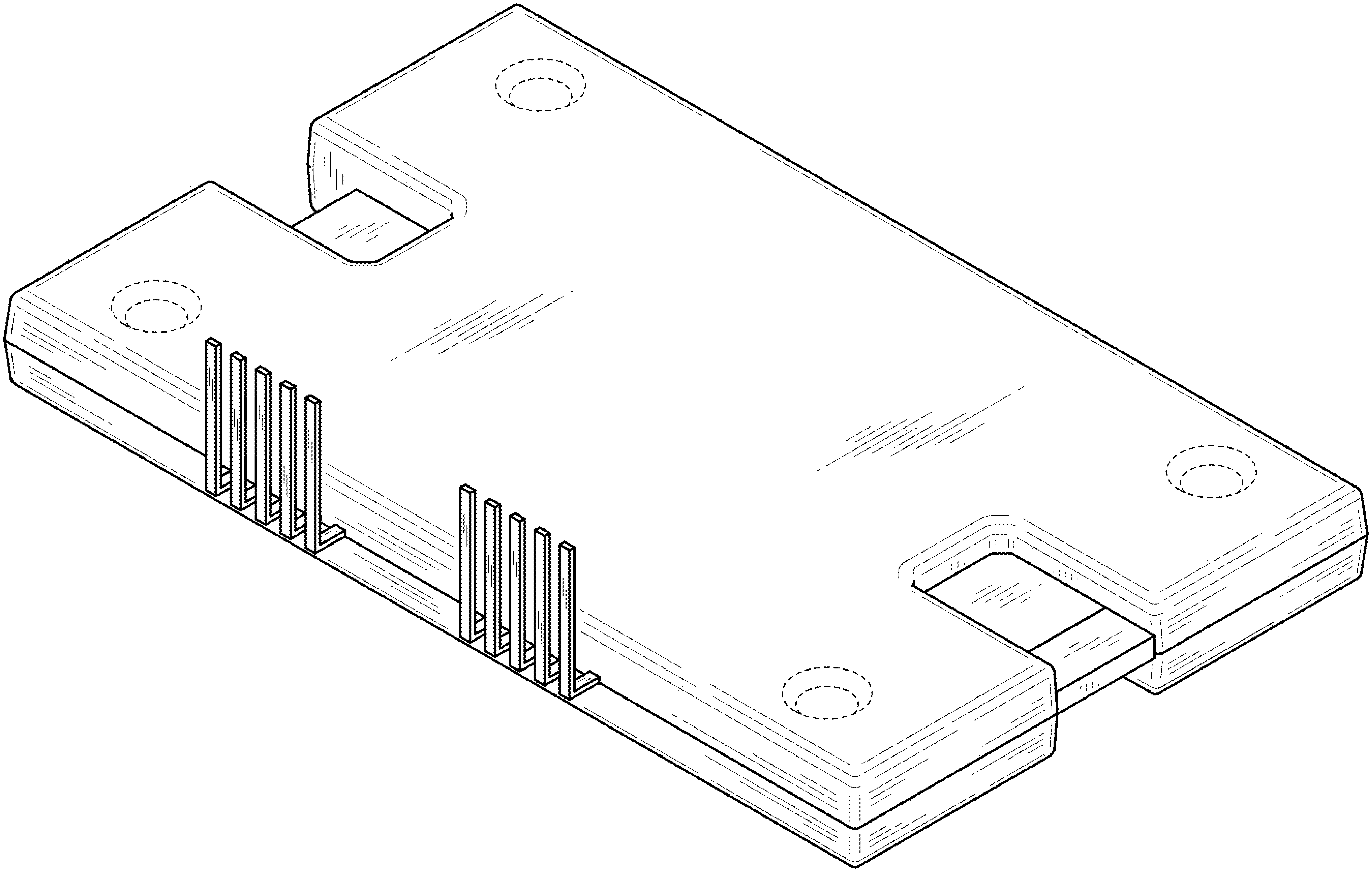
FIG.1



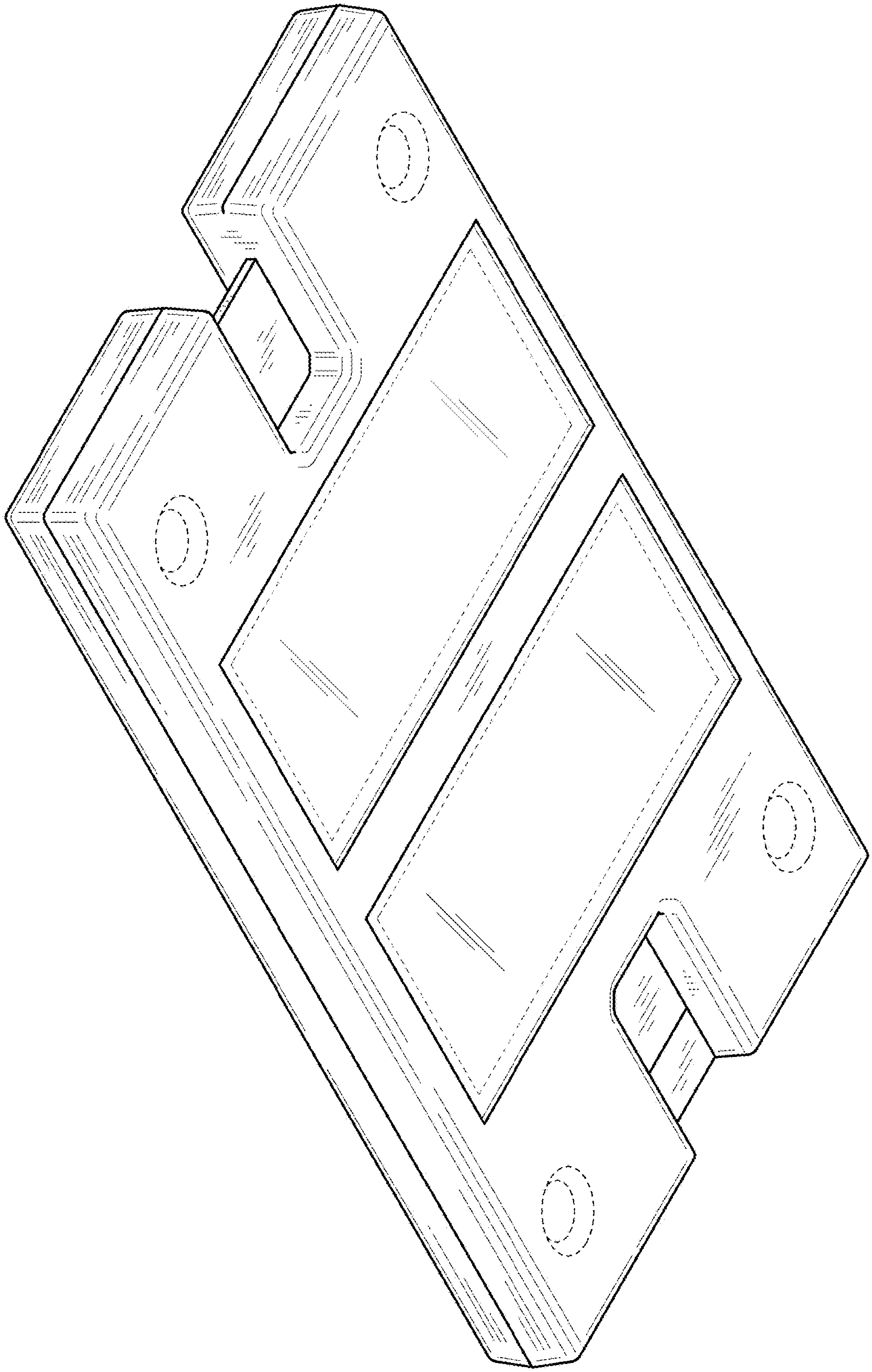


FIG.2

FIG.3

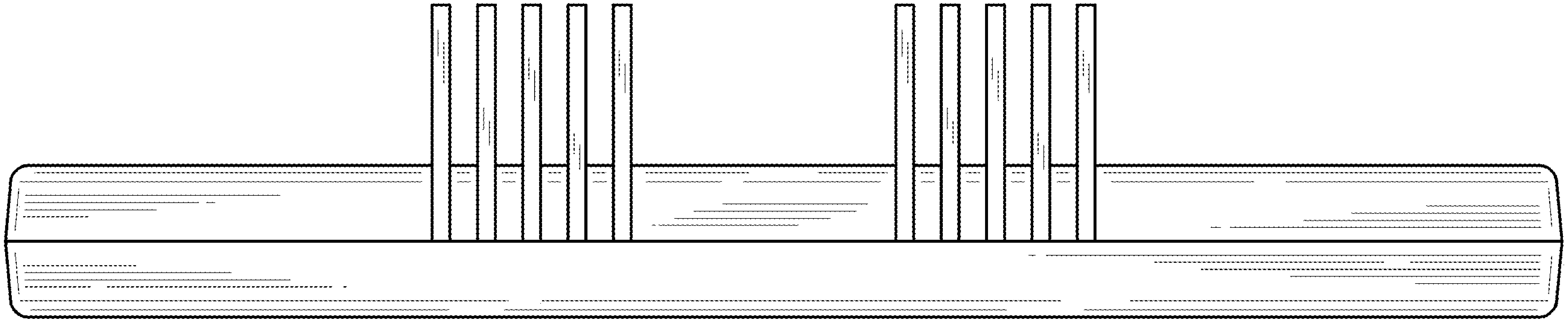


FIG.4

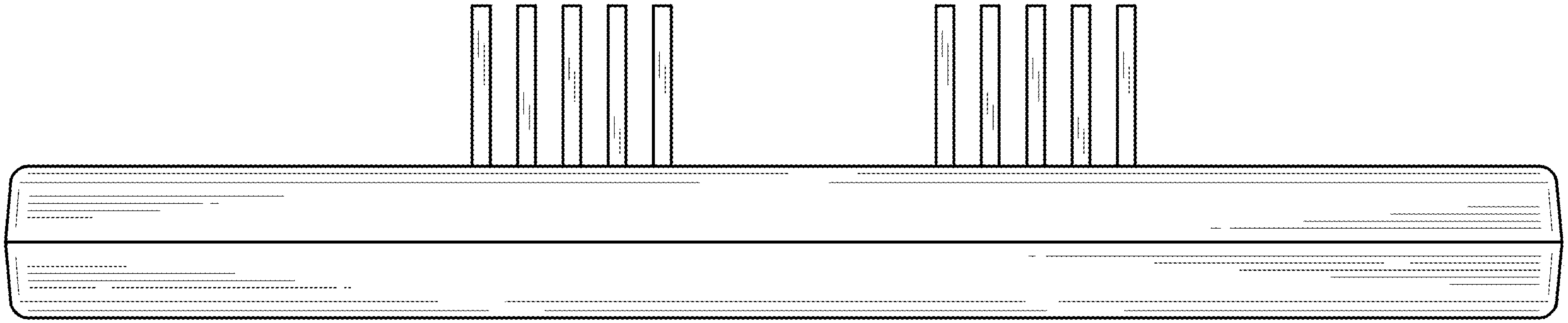
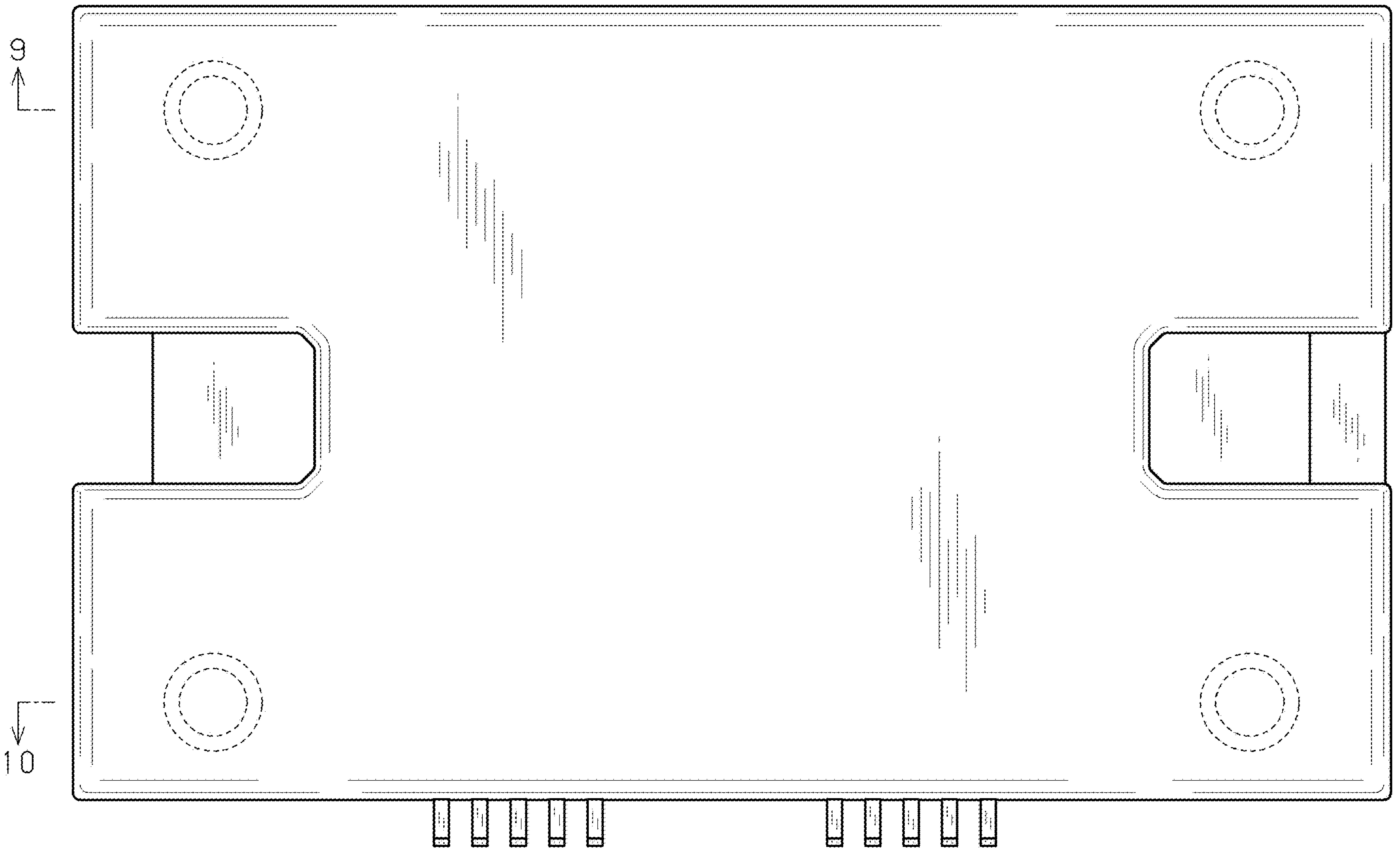


FIG.5



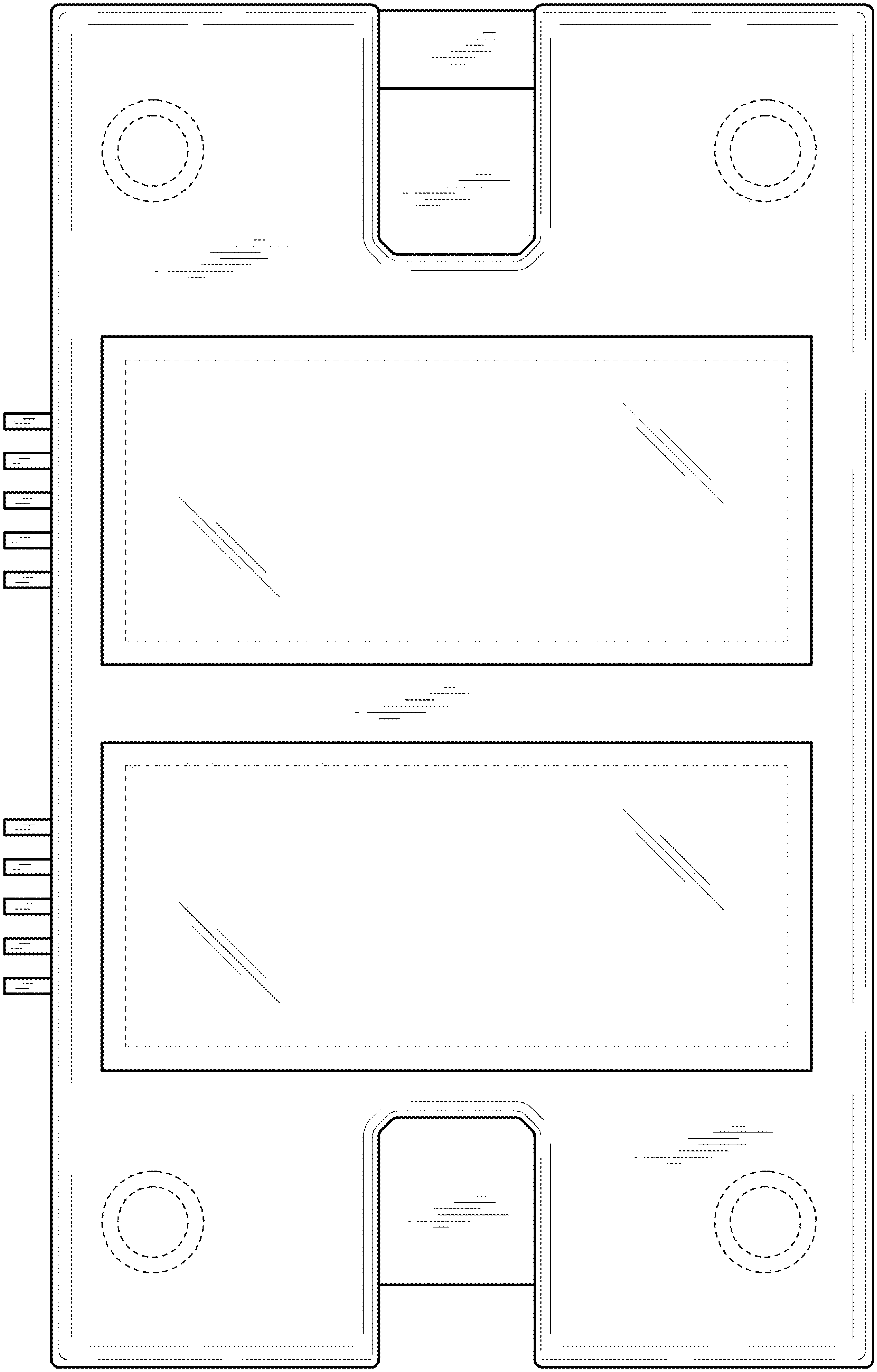


FIG.6

FIG.7

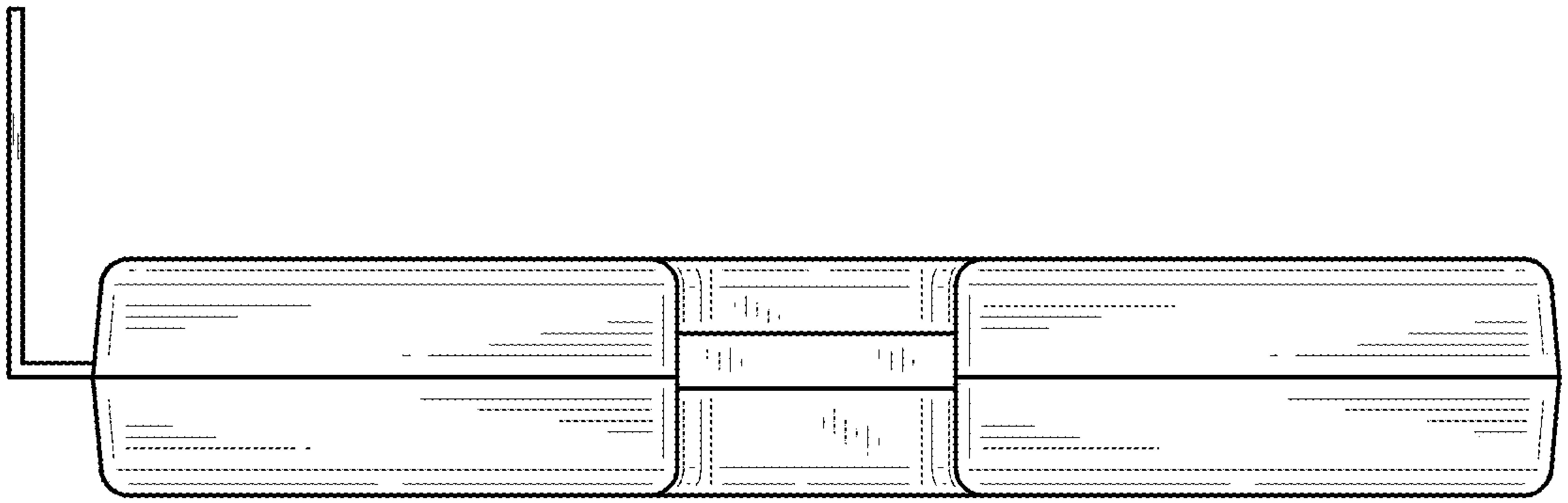


FIG.8

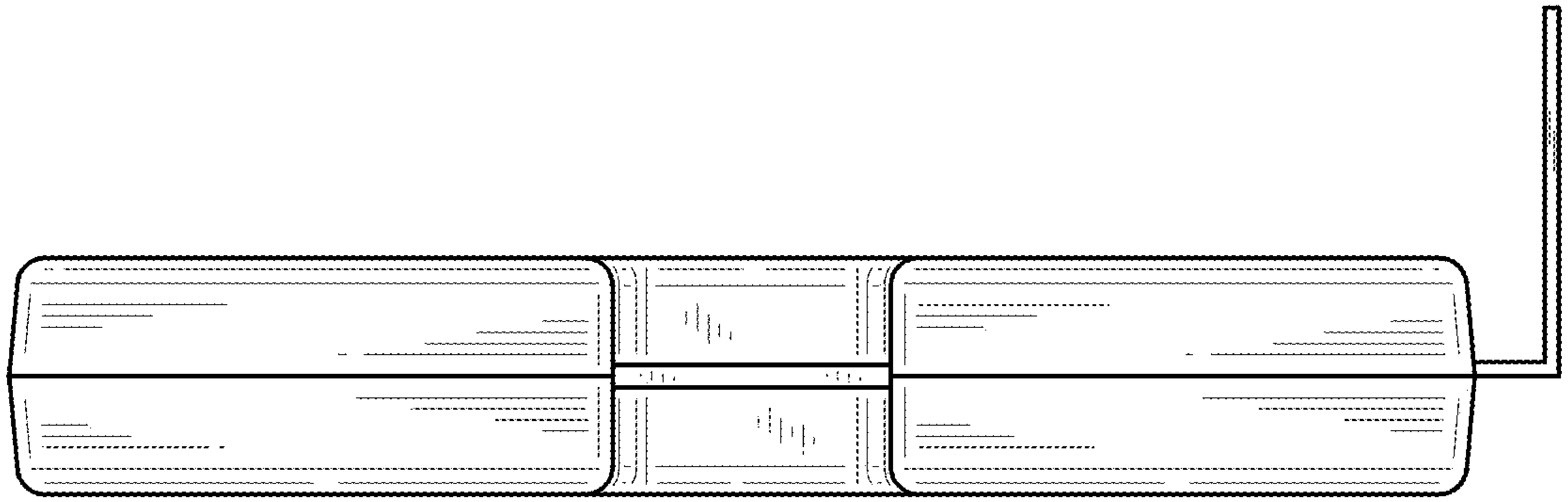


FIG.9

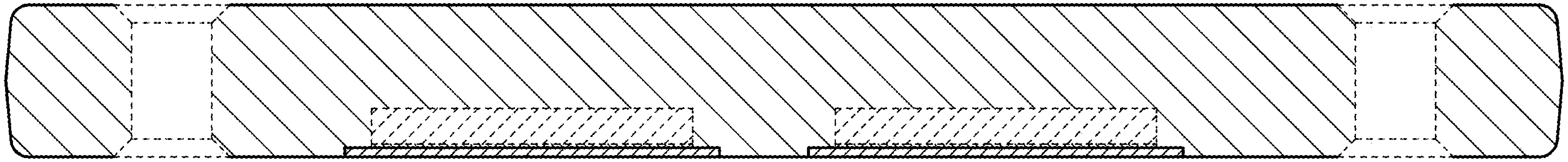


FIG.10

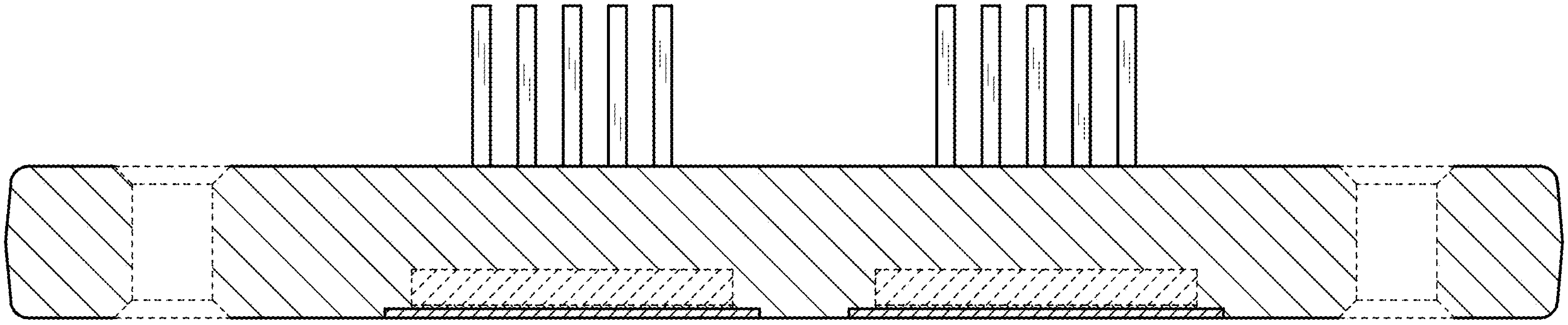
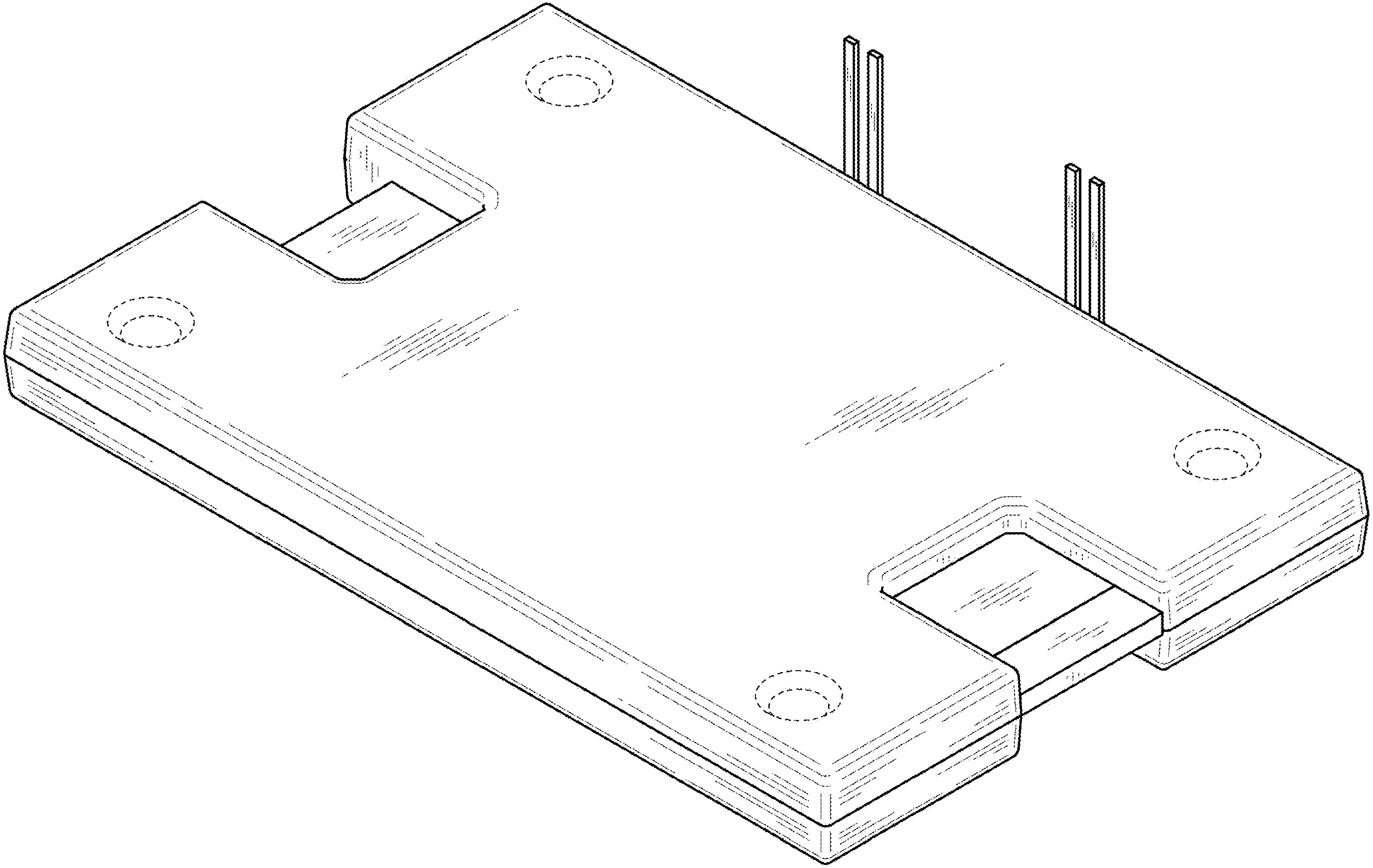


FIG.11



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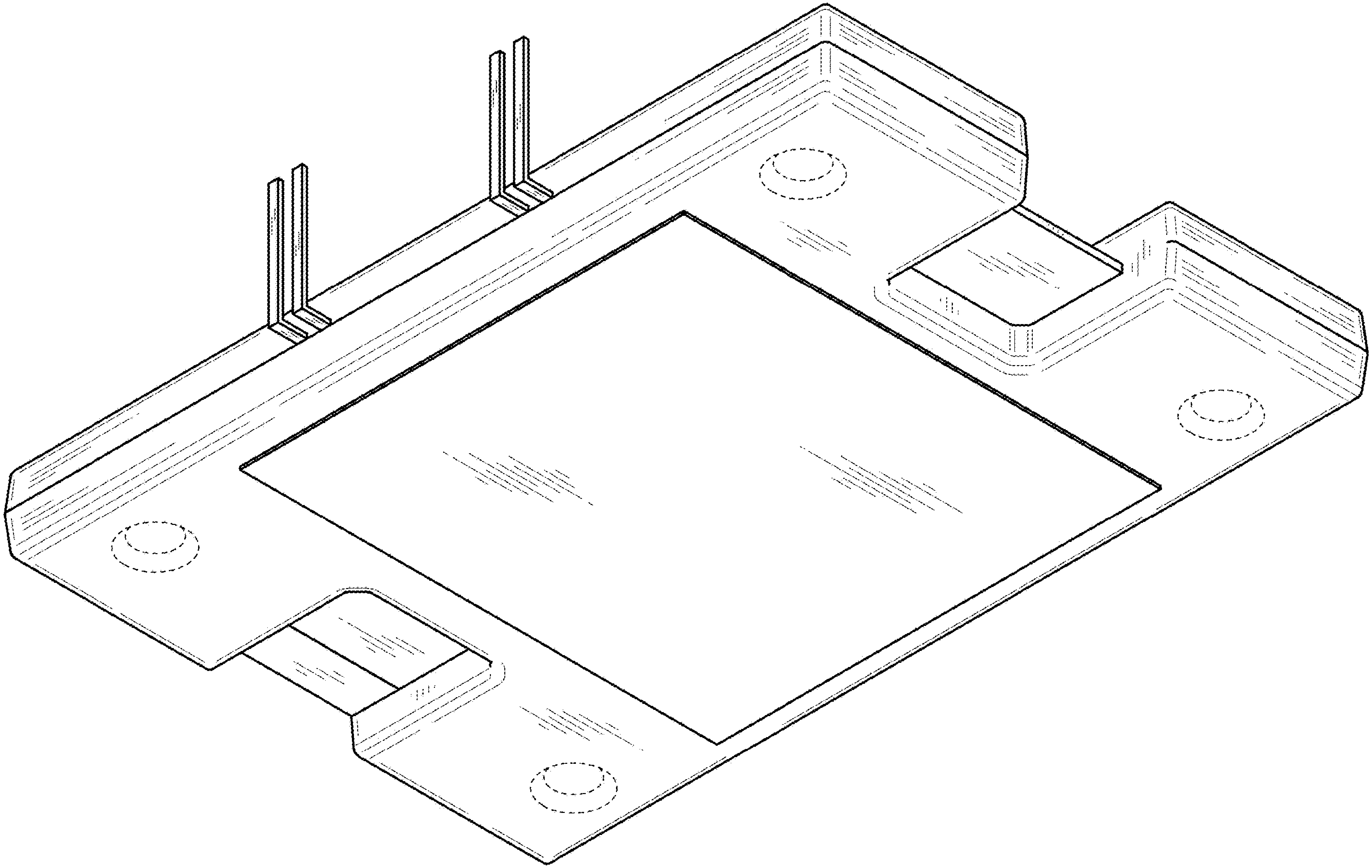


FIG.13

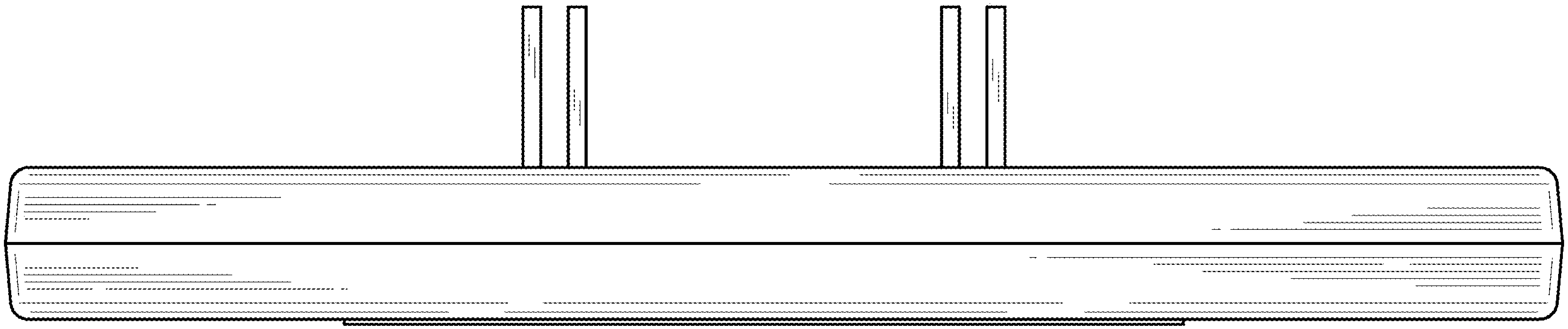
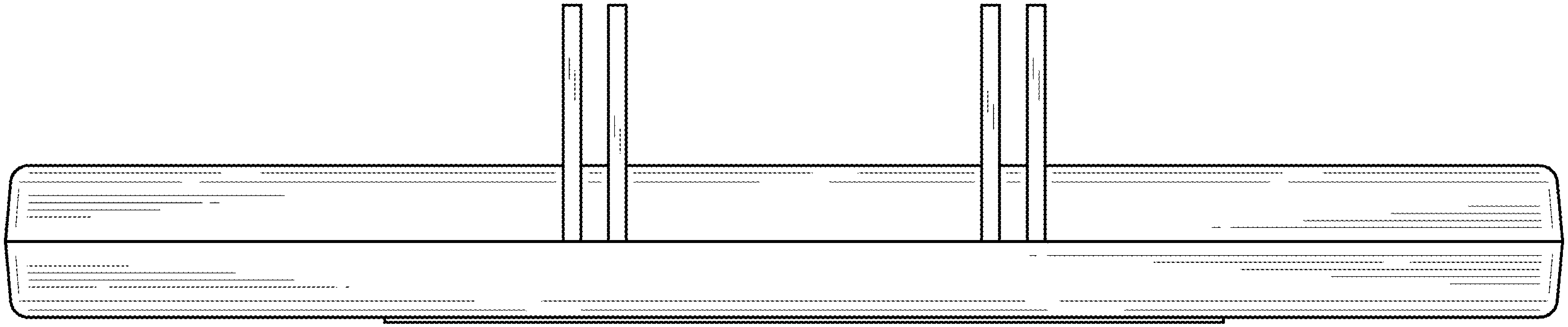


FIG.14



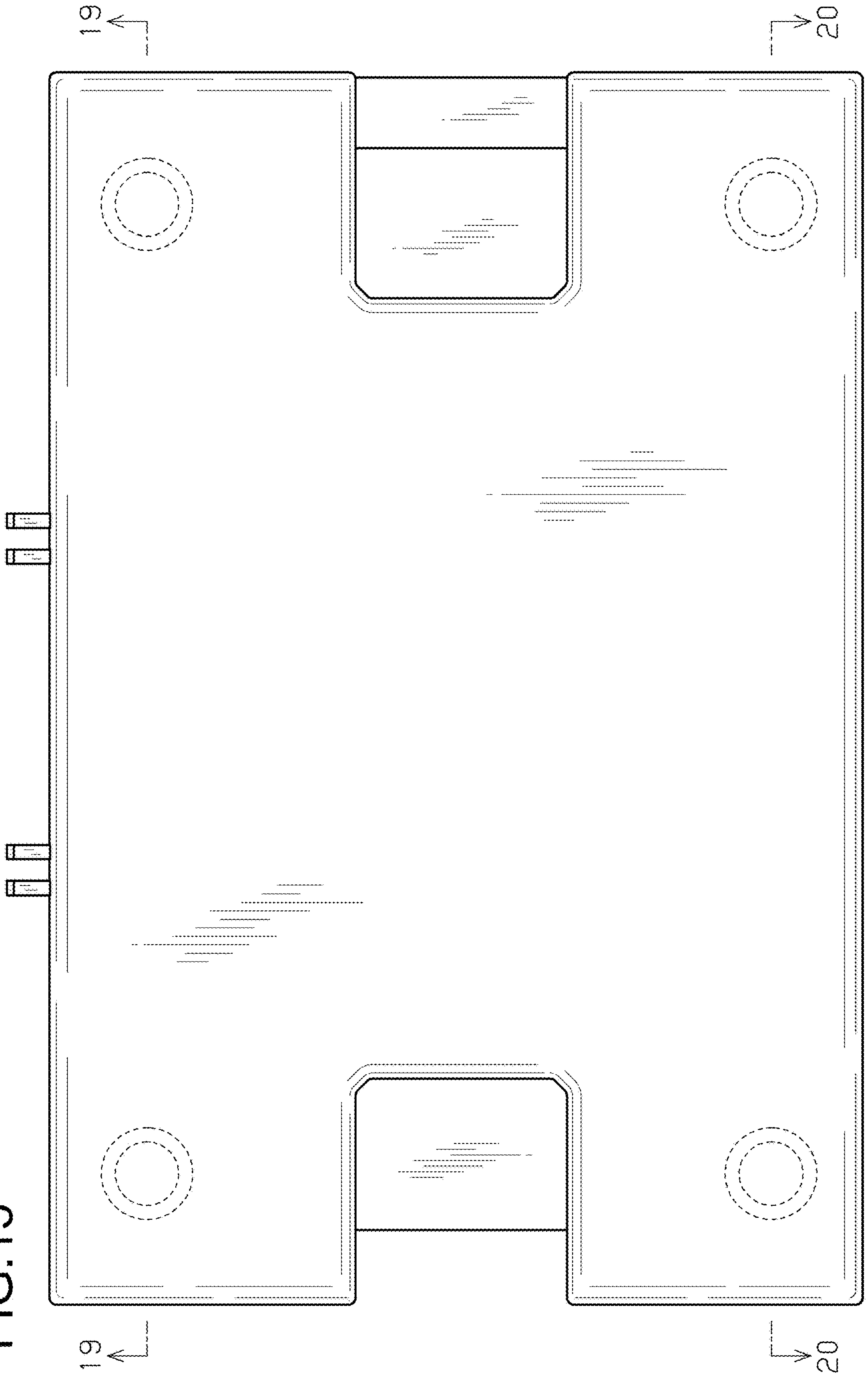


FIG.15

FIG.16

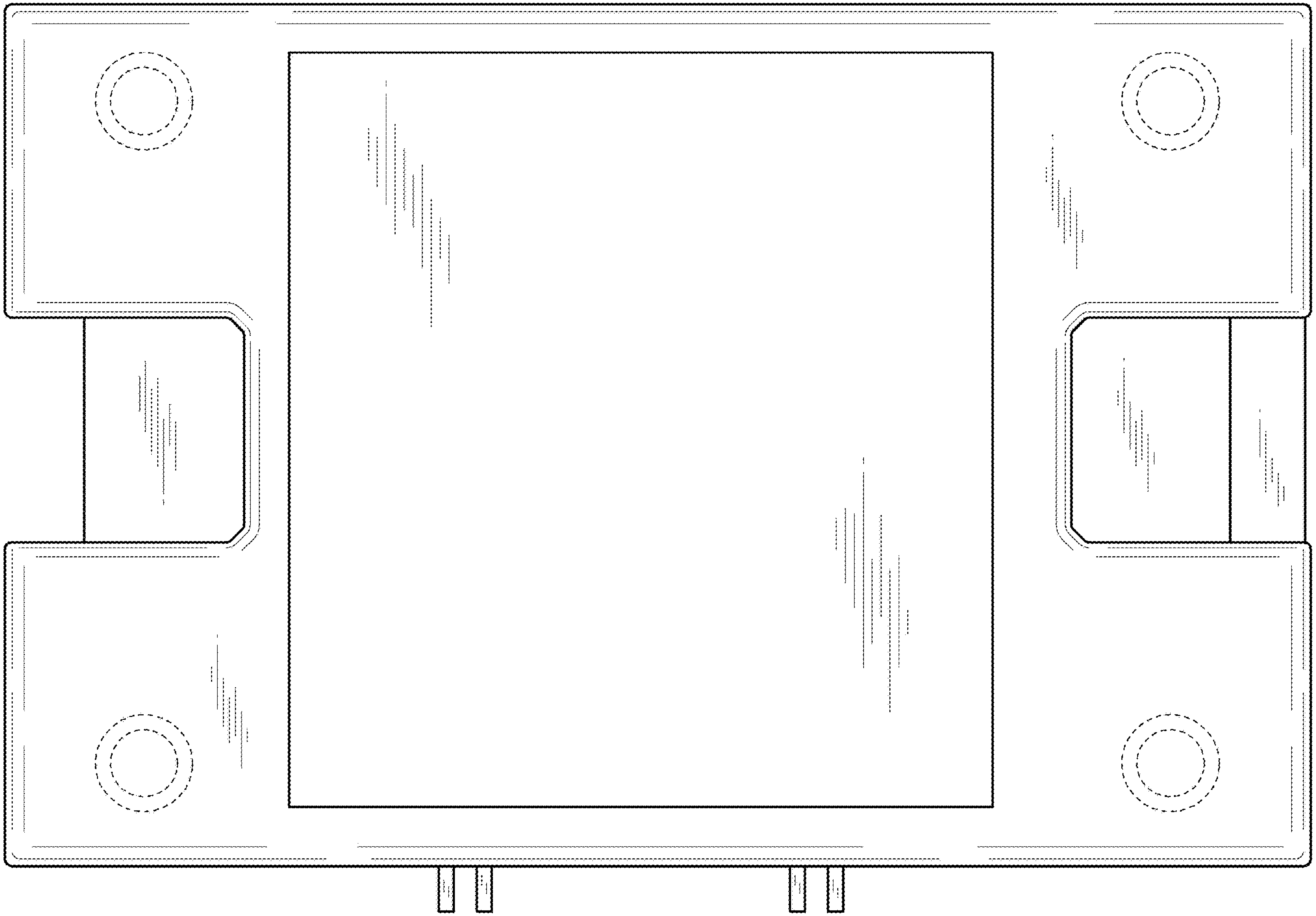
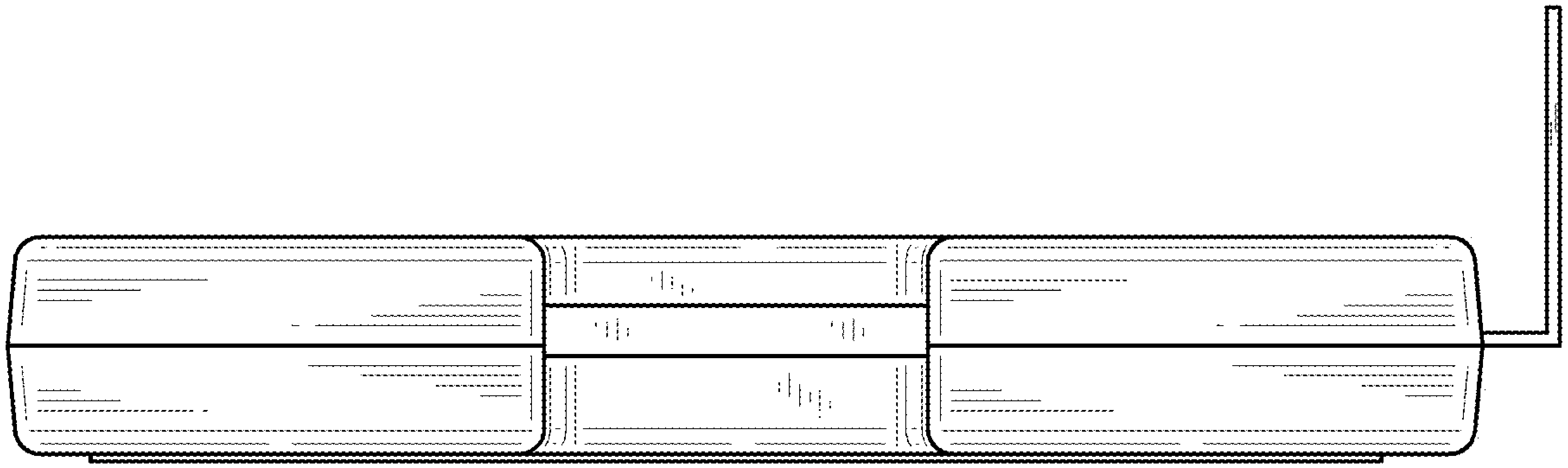


FIG.17



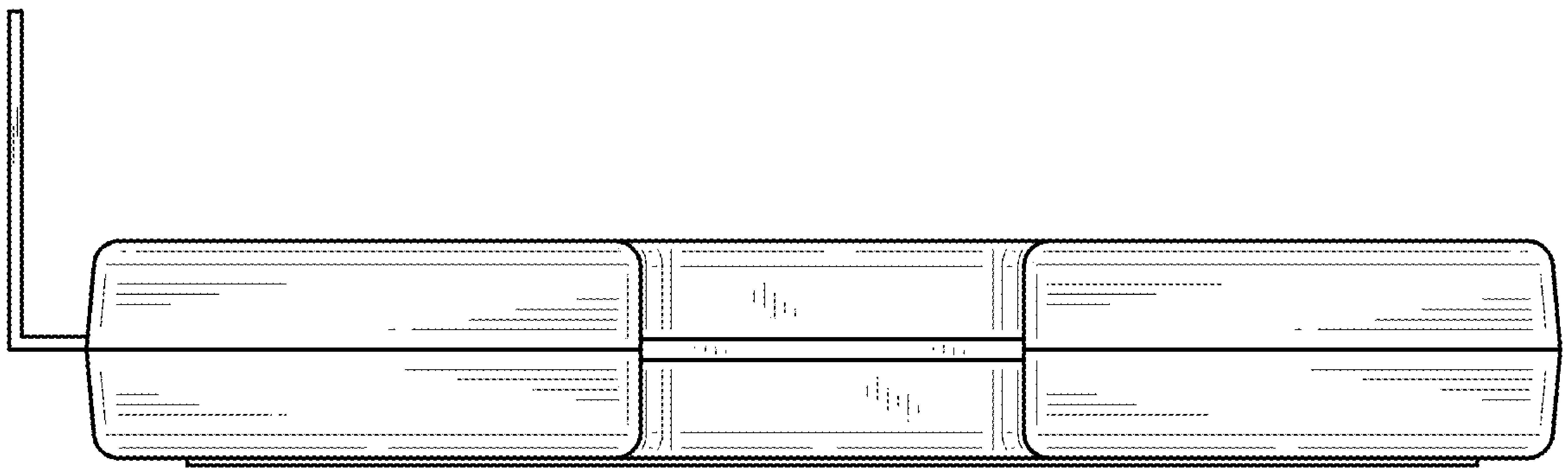


FIG.18

FIG.19

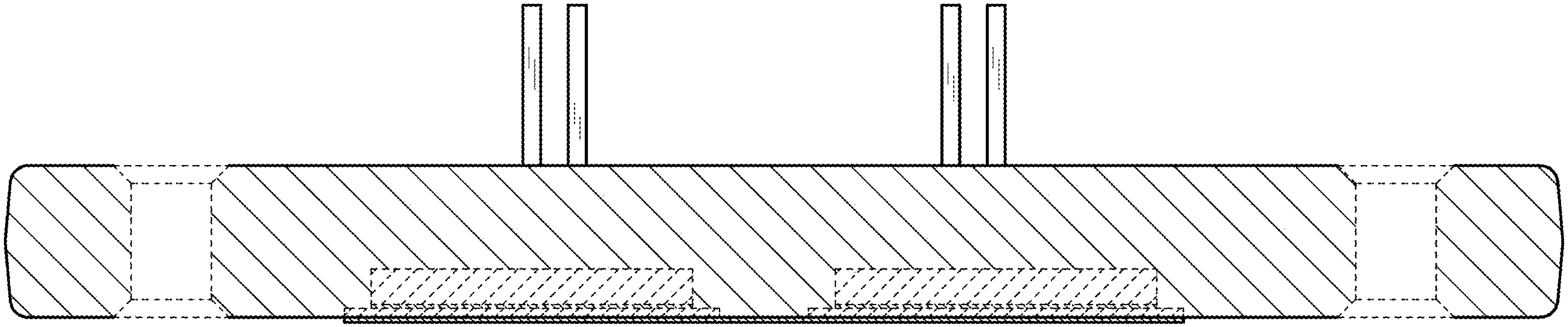


FIG.20